



IEEE International Conference on Engineering Veracruz 2019 (IEEE ICEV 2019)[®] Innovation and Technology Development CALL FOR PAPERS

On behalf of the Organizing Committee, we have the pleasure to invite you to submit your contributions to the IEEE International Conference on Engineering Veracruz 2019 (IEEE ICEV 2019) (IEEE Congreso Internacional de las Ingenierías Veracruz 2019). The conference will be held in the Museo de Ciencia y Tecnología del Estado de Veracruz in Xalapa, Veracruz, Mexico from 14 to 17 October 2019, organized by the Universidad Veracruzana (DGAAT-Dirección General del Área Académica Técnica) and the IEEE Student Branches with the support of the IEEE Veracruz Section and Consejo Veracruzano de Investigación Científica y Desarrollo Tecnológico (COVEICYDET). IEEE ICEV2019 is Technically Sponsored by IEEE. The conference proceedings will be submitted for inclusion in IEEE Xplore. Authors from all over the world are invited to submit original and unpublished papers, which are not under review in any other conference. All papers will be peer reviewed by the technical program committee. Submitted papers must be written in English and should be in PDF format. Paper length must be between 4 and 8 pages.

14 to 17 October 2019

Museo de Ciencia y Tecnología del
Estado de Veracruz

Murillo Vidal # 1735, Zip 91069

Xalapa, Veracruz, Mexico

For more information , visit the
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Topics of Interest

Authors are invited to submit contributions including, but not limited to the following areas:

- Power and Energy Systems
- Materials Science and Engineering
- Nanomedicine and Biomedical Engineering
- Mechanical Engineering
- Electrical Engineering
- Electronics Engineering
- Mechatronics Engineering
- Chemical Engineering
- Computer Systems Engineering
- Energy Harvesting Systems
- Micro and Nanotechnology
- Micro and Nanosystems
- Devices and Sensors: CMOS, MEMS, NEMS
- Modeling and Simulation
- Internet of Things (IoT)
- Electronic Instrumentation Engineering
- Signal Processing Engineering
- Physics and Optical Engineering
- Civil Engineering
- Corrosion Engineering
- Information Technology
- Technological Educational Innovation

The submission Web page for IEEE ICEV 2019 is:
<https://easychair.org/conferences/?conf=ieeeicev2019>.

IMPORTANT INFORMATION

Paper Submission Deadline:	May 1, 2019
Notification of acceptance:	June 21, 2019
Camera-ready due:	July 31, 2019
Payment Deadline:	August 30, 2019
Registration Deadline:	October 14, 2019
Presentation of papers from:	14 to 17 October 2019